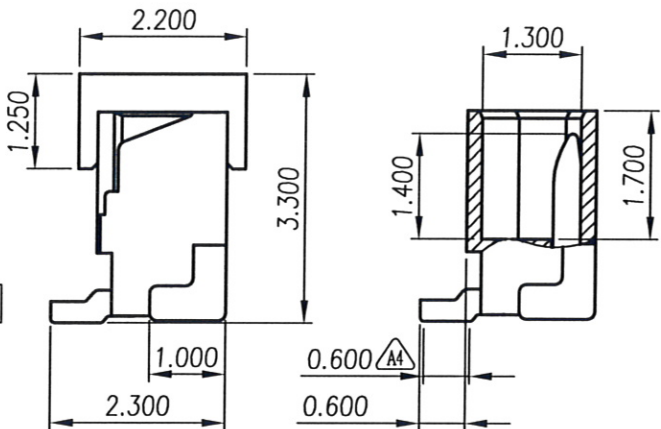
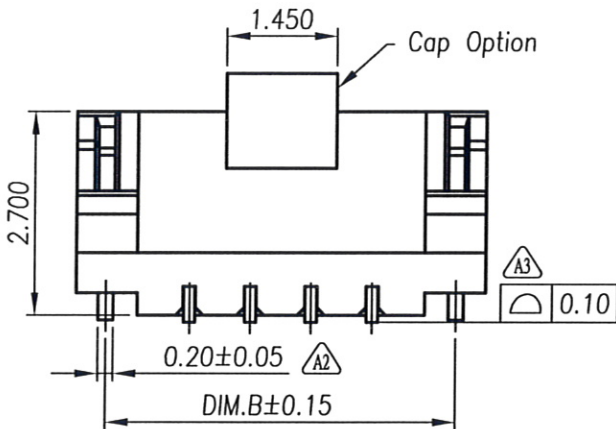
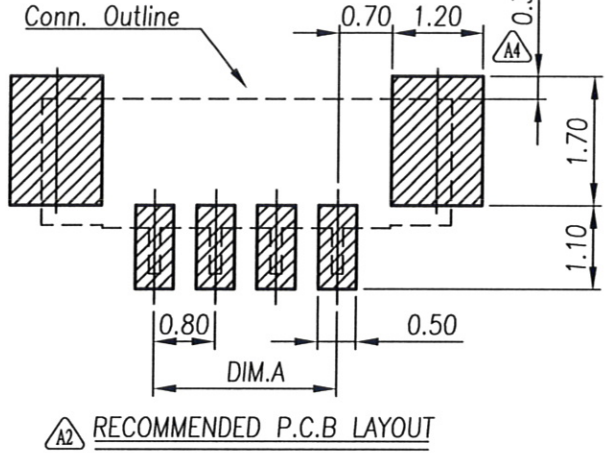
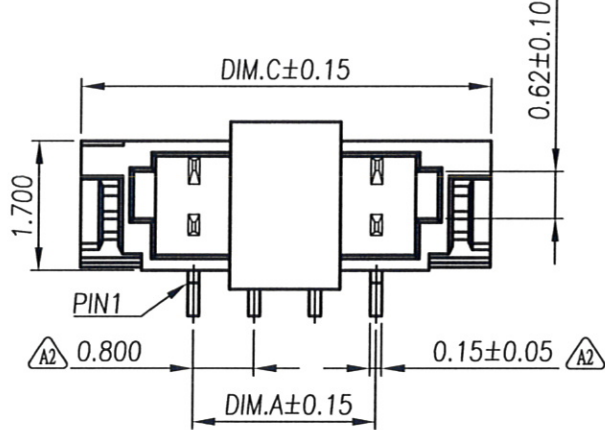


RoHS Compliant



REV	MODIFICATION	DATE	DRAW
A2	Release To ECN20150109	2015.01.26	Michelle
A3	Release To ECN20150705	2015.07.17	Michelle
A4	Release To ECN20150805	2015.08.06	Michelle

Specification  
 1.Current Rating:0.5A AC/DC(AWG32) 0.2A AC/DC(AWG36)  
 2.Voltage Rating:30V AC  
 3.Contact Resistance:20mΩ Max.(Initial) 40mΩ Max.(Final)  
 4.Insulation Resistance:100MΩ Min. At 200V  
 5.Dielectric Withstanding Voltage:AC200V/Minute  
 6.Operating Temperature:-25°C~+85°C

Material:  
 1.Housing:High Temperature Thermoplastic UL94V-0  
 2.Tab:Copper Alloy T=0.20mm  
 3.Contact Pin:Copper Alloy T=0.15mm  
 4.Cap:High Temperature Thermoplastic UL94V-0

Finish:  
 1.Housing:Natural  
 2.Tab:Tin Plated Over Nickel  
 3.Contact Pin:See P/N Option  
 4.Cap:Natural

Part No.: AS09600 XX K X X 1

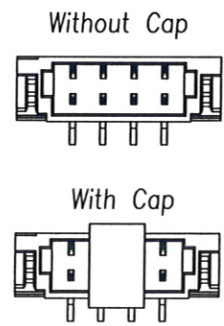
No. Of Pin  
02~20


Packing  
 0:T&R With Cap  
 1:T&R Without Cap  
 3:Tube With Cap  
 4:Tube Without Cap

△A2 Housing Material  
 K:HTN UL94V-0 Natural H.F  
 △A2 Plating  
 2:Matte Tin Plated Over Nickel  
 3:Gold Plated Over Nickel




PIN	DIM.A	DIM.B	DIM.C	PIN	DIM.A	DIM.B	DIM.C
02	0.80	3.00	3.80	10	7.20	9.40	10.20
03	1.60	3.80	4.60	12	8.80	11.00	11.80
04	2.40	4.60	5.40	14	10.40	12.60	13.40
05	3.20	5.40	6.20	15	11.20	13.40	14.20
06	4.00	6.20	7.00	16	12.00	14.20	15.00
07	4.80	7.00	7.80	17	12.80	15.00	15.80
08	5.60	7.80	8.60	20	15.20	17.40	18.20
09	6.40	8.60	9.40				





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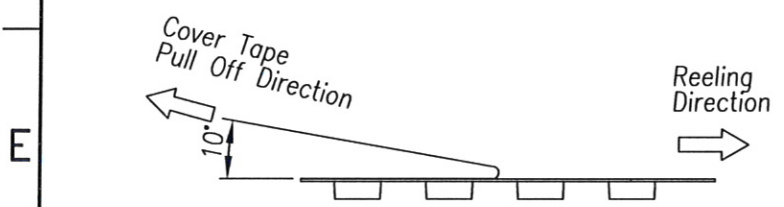
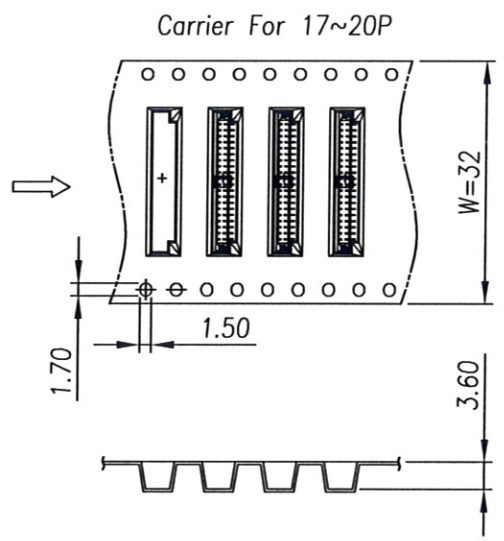
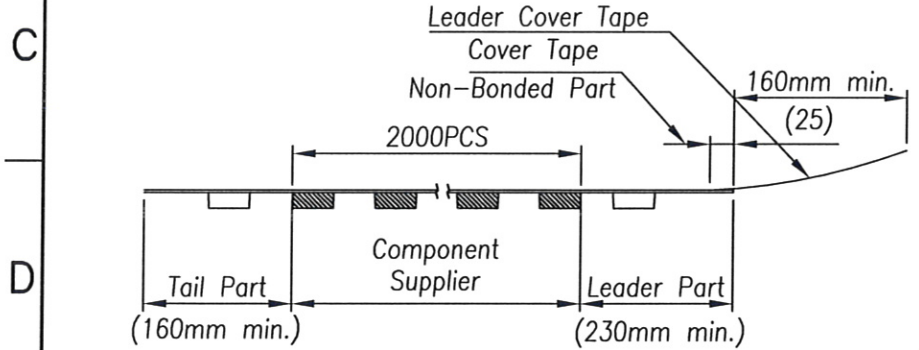
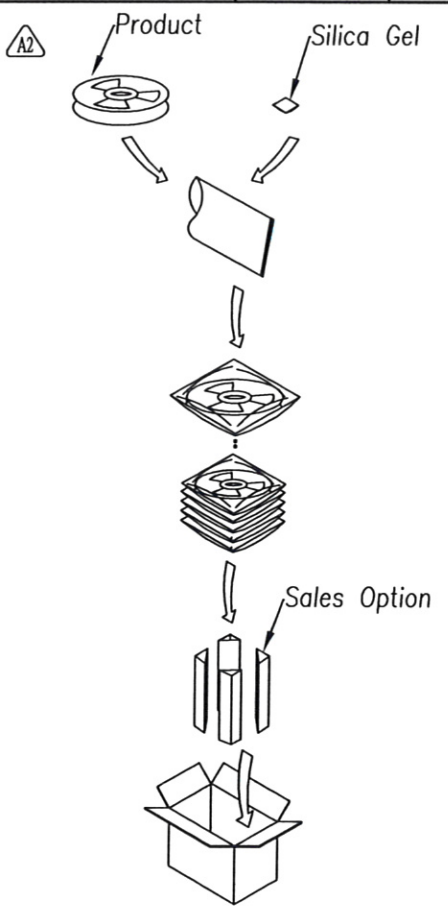
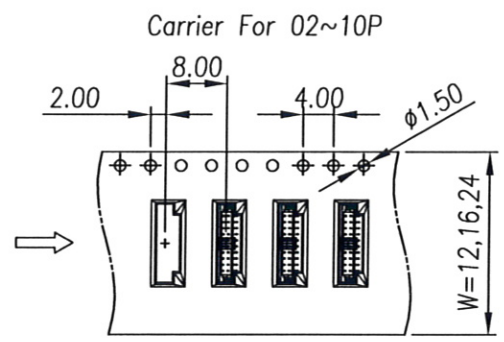
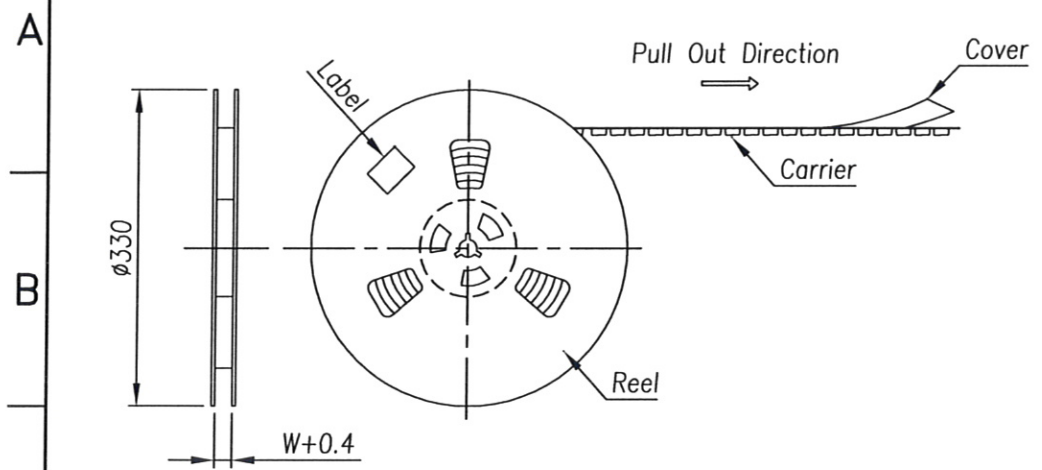
### GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ. 	TITLE: Wire To Board Wafer 0.80mm 180° SMT Single Row	
.x± 0.35	.x'± 2'	APR. C.F.Liao 20150806	PART NO. AS09600XXKXX1	DWG NO. AS09600XXKXX1
.xx± 0.25	.x'± 1'	CHK. Abel 20150806	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20150806	SIZE: A4	SCALE 10:1
		SHEET 1 / 2		REV A4

RoHS Compliant




REV	MODIFICATION	DATE	DRAW
A2	Release To ECN20150109	2015.01.26	Michelle
A3	Release To ECN20150705	2015.07.17	Michelle
A4	Release To ECN20150805	2015.08.06	Michelle




PIN NO.	W ±0.30	PCS / REEL
02.03.04	12	2000
05.06.07.08	16	
10	24	
17.20	32	

Notes:  
 1. Material : PS  
 2. Part No.: AS09600XXKX01  
 AS09600XXKX11



## 金上達科技股份有限公司

GOLDENSUND TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ. 	TITLE: Wire To Board Wafer 0.80mm 180° SMT Single Row	
.x± 0.35	x.*± 2'	APR. C.F.Liao 20150806	PART NO. AS09600XXKXX1	DWG NO. AS09600XXKXX1
.xx± 0.25	.x.*± 1'	CHK. Abel 20150806	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx.*± 0.5'	DRA. Michelle 20150806	SIZE: A4	SCALE Free
			SHEET 2 / 2	REV A4